

Amkor Package Capability

Hermetic

Package Type & Body Size	Leadcount and Pitch	Factory
CBGA		
Ceramic Ball Grid Array	All	P1
CPGA		
Ceramic Pin Grid Array	All	P1
CQFP		
Ceramic Quad Flat Pack	24, 28, 32, 40, 44, 64, 80, 84, 92, 100, 128, 132, 144, 152, 160, 164, 172, 196, 228, 240, 320, 340	P1
Ceramic SOIC		
Small Outline IC	28, 40	P1
Ceramic SSOP		
Shrink Small Outline Package	20, 24	P1
Ceramic ZIP/SIP		
	6, 20	P1
Cerdip		
.300"	8, 14, 16, 18, 20, 24, 28	P1
.400"	22, 24	P1
.600"	24, 28, 32, 40,	P1
Cerpak		
	10, 14, 16, 20, 24, 28, 32, 44, 48, 56	P1
"J" Cerquad		
"J" Lead Ceramic Quad	28, 32, 44, 48, 52, 64, 68, 84	P1
LCC		
Leaded Chip Carrier	8, 10, 12, 14, 16, 18, 20, 24, 28	P1
LLCC		
Leadless Chip Carrier/Flatpak	16, 18, 20, 24, 28, 32, 42, 44, 64, 68, 84, 88, 100, 132, 172, 196, 224, 225, 240, 256	P1
LCPGA		
Low Cost Pin Grid Array	All	P1
PPGA		
Plastic Pin Grid Array	All	P1
Side Braze		
.300"	14, 16, 18, 20, 24, 28	P1
.400"	22	
.600"	24, 28, 32, 40, 42, 48, 52, 64	

P1 = Muntinlupa City, Philippines

www.amkor.com



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This listing contains information relating to package type, body size, leadcount, pitch and factory location that was accurate when published, however some of these parameters may change before this listing is again updated.